

In the Claims:

Please amend the claims to appear as follows:

15. A method of mounting an electrical connector to a substrate, comprising:
providing an electrical connector having a contact and a hold down;

providing a substrate having a pad;
securing said contact to said pad on said substrate during a reflow

process;

W
place
hold
down
into
hole
substrate
so
as
to
permit
said
contact
center
on
said
pad
upon
mounting
to
the
substrate
without
contacting
another
pad
on
the
substrate,
wherein
said
hold
down
is
adapted
to
retain
said
housing
a
distance
from
a
surface
of
the
substrate;
and

securing
said
hold
down
to
said
substrate
during
said
reflow
process,
wherein
said
hold
down
is
manufactured
to
secure
to
said
substrate
subsequent
to
said
securing
of
said
contact,
wherein
said
hold
down
is
adapted
to
limit
flattening
of
said
contact
during
said
reflow
process.

42. A connector/substrate combination manufactured by the following steps:
providing an electrical connector having a contact and a hold down;

providing
a
substrate
having
a
pad;
securing
said
contact
to
said
pad
on
said
substrate
during
a
reflow
process;

placing
said
hold
down
into
a
hole
in
said
substrate
so
as
to
permit
said
contact
center
on
said
pad
upon
mounting
to
the
substrate
without
contacting
another
pad
on
the
substrate,
wherein
said
hold
down
is
adapted
to
retain
said
housing
a
distance
from
a
surface
of
the
substrate;
and